

APPLICATION DATA SHEET

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Title of Invention	SEMICONDUCTOR PACKAGE FOR A LARGE DIE							
Application Type: regular, utility Attorney Docket Number: 27-010								
Correspondence address: Customer Number: 22898 *22898*								
Inventor Information: Inventor 1: Applicant Authority Type: Inventor Citizenship: CA Given Name: Kambhampati Family Name: Ramakrishna City of Residence: Tempe State of Residence: AZ Country of Residence: US Address-1 of Mailing Address: 1711 W. Greentree Dr. Address-2 of Mailing Address: City of Mailing Address: Tempe State of Mailing Address: AZ Postal Code of Mailing Address: 85284 Country of Mailing Address: US Phone: Fax: E-mail:								
Attorney Information:								
<table border="1"><thead><tr><th>Name</th><th>Registration Number</th></tr></thead><tbody><tr><td>Mikio ISHIMARU</td><td>27449</td></tr><tr><td>William D. ZAHRT II.</td><td>26070</td></tr></tbody></table>			Name	Registration Number	Mikio ISHIMARU	27449	William D. ZAHRT II.	26070
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Publication Information:**Suggested Figure for Publication - FIG. 6****Suggested Classification -****Suggested Technology Center -****Total Number of Drawing Sheets - 7****Assignee 1:****Organization Name: ST ASSEMBLY TEST SERVICES LTD.****Address-1 of Mailing Address: 5 Yishun St. 23****Address-2 of Mailing Address:****City of Mailing Address: Singapore****State of Mailing Address:****Postal Code of Mailing Address: 768442****Country of Mailing Address: SG****Phone:****Fax:****E-mail:**